

## Platamid® HX 2667 Powder

Copolyamide Hot Melt Adhesive / Textile Applications

**Platamid® HX 2667 Powder** is a medium melt viscosity copolyamide adhesive powder for the production of fusible interlinings.

**Platamid® HX 2667 Powder** offers excellent laundry resistance up to 60°C and an excellent resistance to all kind of steam treatment.

| PROPERTIES                    | DRY / COND | UNIT                    | TEST STANDARD  |
|-------------------------------|------------|-------------------------|----------------|
| <b>RHEOLOGICAL PROPERTIES</b> |            |                         |                |
| Melt Volume-Flow Rate         | 30 / *     | cm <sup>3</sup> /10 min | ISO 1133       |
| Temperature                   | 160 / *    | °C                      | -              |
|                               | 320 / *    | °F                      | -              |
| Load                          | 2.16 / *   | kg                      | -              |
|                               | 4.76 / *   | lb                      | -              |
| <b>THERMAL PROPERTIES</b>     |            |                         |                |
| Melting Temperature, 10°C/min | 128 / *    | °C                      | ISO 11357-1/-3 |

## AVAILABLE GRADES

This grade is available in different grain sizes:

- Platamid® HX 2667 PA80 (0-80 µm paste dot)
- Platamid® HX 2667 PTA 170/20 (0-170 µm power dot)
- Platamid® HX 2667 PTA 170 (80-170 µm double dot)

## PACKAGING

- Platamid® HX 2667 PA80 and Platamid® HX 2667 PTA 170/20 are delivered in 20 kg sealed bags.
- Platamid® HX 2667 PTA 170 is delivered in 20 kg sealed bags.

## SHELF LIFE

Two years from the date of delivery. For any use above this limit, please refer to our technical services.

|                                                                                                                  |                                                                                                                                         |
|------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| <b>PROCESSING</b><br>Scattering, Paste, Double Dot                                                               | Headquarters:<br>Arkema France<br>420 rue d'Estienne d'Orves<br>92705 Colombes Cedex France<br>T +33 (0)1 49 00 80 80<br>hpp.arkema.com |
| <b>DELIVERY FORM</b><br>Powder                                                                                   |                                                                                                                                         |
| <b>SPECIAL CHARACTERISTICS</b><br>Adhesive, Bio-Based                                                            |                                                                                                                                         |
| <b>REGIONAL AVAILABILITY</b><br>North America, Europe, Asia Pacific, South and Central America, Near East/Africa |                                                                                                                                         |

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